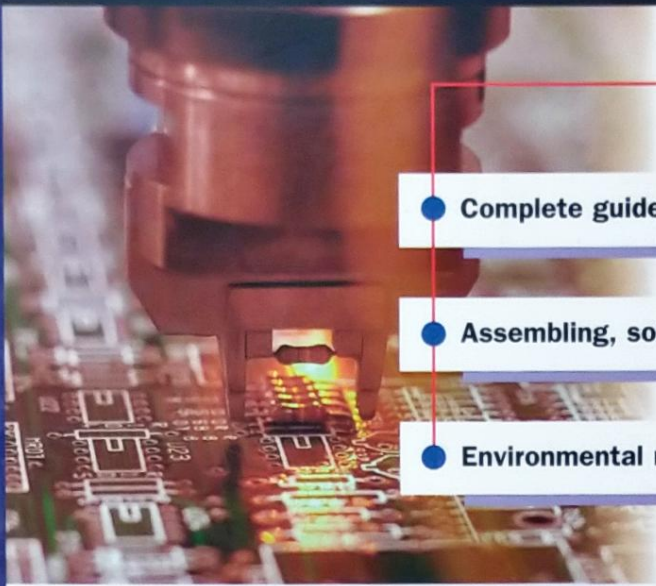


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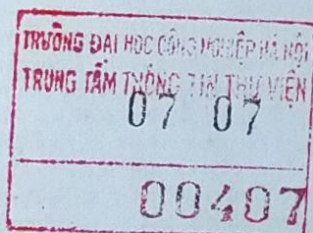
Chips, Circuit Boards, Packages, and Components

Charles A. Harper Editor-in-Chief
Technology Seminars, Inc., Lutherville, Maryland

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CONTENTS

Preface	xi
Contributors	xiii
Dedication	xv

Chapter 1 Printed Circuit History and Overview 1

Ken Gilio

1.1	Introduction	1
1.2	Circuit Technology	4
1.3	Circuit Materials	21
1.4	Circuit Processes	26
1.5	Circuit Construction and Types	32
1.6	Circuitry for Electronic Packages	40
1.7	Printed Circuit Trends	45
1.8	The Printed Circuit Business and Economics	46
1.9	Long-Term Expectations	46
1.10	Acknowledgments	48
1.11	References	48
1.12	Bibliography	49

Chapter 2 Development and Fabrication of IC Chips 51

Charles Cohn

2.1	Introduction	51
2.2	Atomic Structure	52
2.3	Vacuum Tubes	55
2.4	Semiconductor Theory	58
2.5	Fundamentals of Integrated Circuits	70
2.6	IC Chip Fabrication	78
2.7	References	103

Chapter 3 Packaging of IC Chips..... 105

Charles Cohn

3.1	Introduction	105
3.2	The IC Package	106
3.3	Package Families	108
3.4	Package Technologies	117
3.5	Comparison of Package Technologies	153
3.6	IC Assembly Processes	156
3.7	Summary and Future Trends	186
3.8	References	188

Chapter 4 Laminates and Prepregs as Circuit Board

Base Materials 191

Doug Sober

4.1	Introduction	191
4.2	Paper-Based Materials	192
4.3	FR-4 Materials	194
4.4	Composite Materials	199
4.5	High-Performance Materials	203
4.6	Microvia Materials	205
4.7	High-Speed/High-Frequency Materials	207
4.8	Conclusion	208

Chapter 5 Printed Circuit Board Fabrication 211

Joseph Fjelstad

5.1	Introduction	211
5.2	Background and History	212
5.3	Materials of Construction	216
5.4	Laminate Material Preparation	223
5.5	Lamination Methods	223
5.6	Laminate Forms for PCBs	225
5.7	Laminate Selection	228
5.8	Solder Masks	228
5.9	Generic Processes Overview for a Plated-Through-Hole Printed Circuit	231
5.10	Additive and Subtractive Processing	241
5.11	Single-Sided Circuit Process Examples	242
5.12	Double-Sided Circuit Process Examples	245
5.13	Standard Multilayer Circuit Process Example	247
5.14	Mass Lamination	251
5.15	Metal-Core Printed Circuit Boards	252
5.16	Flexible Circuits	254
5.17	High-Density Interconnection (HDI) Structures	257
5.18	Future Directions	265
5.19	Summary	265
5.20	References	265

Chapter 6 Package and Component Attachment and Interconnection 267

Charles G. Woychik

6.1	Introduction	267
6.2	Levels of Interconnections	268
6.3	Types of First-Level Interconnections	269
6.4	Types of Second-Level Interconnections	272
6.5	Ceramic Packages	279

6.6	Organic Packages	281
6.7	Module-Level Assembly	283
6.8	Ceramic Flip Chip Modules	284
6.9	Organic Flip Chip Modules	286
6.10	Organic Wire Bond Modules	289
6.11	Second-Level Assembly	292
6.12	Migration to Pb-Free Solders and Soldering Processes	301
6.13	References	303

Chapter 7 Solder Materials and Processes for Electronic Assembly Fabrication 305

Jennie S. Hwang, Ph.D.

7.1	General Trends	305
7.2	Solder Materials	309
7.3	Physical Properties	313
7.4	Metallurgical Properties	315
7.5	Mechanical Properties	316
7.6	Solder Alloy Selection—General Criteria	317
7.7	Lead-Free	317
7.8	Reflow Soldering	328
7.9	Inert and Reducing Atmosphere Soldering	340
7.10	Printing	344
7.11	PCB Surface Finish	347
7.12	“Green” Manufacturing	357
7.13	References	358
7.14	Suggested Readings	359

Chapter 8 Printed Wiring Board Cleaning 363

William G. Kenyon

8.1	Introduction	363
8.2	Board Fabrication	368
8.3	Solder Mask over Bare Copper	379
8.4	Solder Mask over Tin-Lead	397
8.5	Environmental Controls and Considerations	402
8.6	Regulatory (OSHA and EPA) Considerations	415
8.7	Applicable Documents	424
8.8	Source and Reference Materials	426
8.9	Acknowledgements and Thanks	427

Chapter 9 Board Coating Materials and Processes 429

John Waryold, Edward B. Mines

9.1	Introduction	429
9.2	Purpose and Function of Conformal Coatings	430
9.3	Specifications that Address Conformal Coatings	430

9.4	Generic Types of Coating Materials	430
9.5	Criteria for the Selection of a Generic Coating Type	433
9.6	Engineering or Performance Aspects	433
9.7	Processing or Application Aspects	435
9.8	Basic Prerequisites for Optimal Coating Performance	437
9.9	Conformal Coating Application Methods	441
9.10	Multiple Coats	445
9.11	Health and Safety Considerations Government Regulations	449
9.12	References	450

Chapter 10 Flexible and Rigid Flexible Fabrication

Process	453
--------------------------	------------

Martin W. Jawitz, Michael J. Jawitz

10.1	Introduction	453
10.2	Classification	454
10.3	Flexible Materials	456
10.4	Fabrication Processes	459
10.5	References	482

Chapter 11 Fabrication and Properties of Electronic

Ceramics and Composites	483
--	------------

Jerry E. Sergent

11.1	Introduction	483
11.2	Surface Properties of Ceramics	486
11.3	Thermal Properties of Ceramic Materials	490
11.4	Mechanical Properties of Ceramic Substrates	494
11.5	Electrical Properties of Ceramics	500
11.6	Ceramic Fabrication	503
11.7	Ceramic Materials	506
11.8	Composite Materials	515
11.9	Forming Ceramics and Composites to Shape	524
11.10	References	526

Chapter 12 Hybrid Microelectronics and Multichip

Module Technologies	529
--------------------------------------	------------

Jerry E. Sergent

12.1	Introduction	529
12.2	Thick Film Technology	530
12.3	Screen Printing	538
12.4	Drying	548
12.5	Firing	549
12.6	Cermet Thick Film Conductor Materials	555
12.7	Thick Film Resistor Materials	559

12.8	Thick Film Dielectric Materials	567
12.9	Overglaze Materials	570
12.10	Thick Film—Conclusions	571
12.11	Thin Film Technology	571
12.12	Thin Film Materials	577
12.13	Comparison of Thick and Thin Film	580
12.14	Copper Metallization Technologies	581
12.15	Summary of Substrate Metallization Technologies	590
12.16	Resistor Trimming	590
12.17	Assembly of Hybrid Circuits	601
12.18	Packaging	612
12.19	Design Of Hybrid Circuits	621
12.20	Multichip Modules	625
12.21	References	629

Chapter 13 Environmental Considerations in Electronic Assembly Fabrication

John W. Lott

13.1	Introduction	631
13.2	Material Considerations	636
13.3	Processes for Environmentally Conscious Manufacturing ..	640
13.4	Regulatory and Nonregulatory Considerations	648
13.5	Summary	654
13.6	References	654

Index	659
About the Editor	672